DOSEMI

IGBT

DG30X07T2LR

650V/30A IGBT with Diode

General Description

DOSEMI IGBT Power Discrete provides ultra low conduction loss as well as low switching loss. They are designed for the applications such as general inverters and UPS.

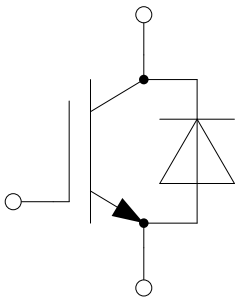
Features

- Low $V_{CE(sat)}$ Fast IGBT technology
- 6μs short circuit capability
- Low switching loss
- Maximum junction temperature 175°C
- $V_{CE(sat)}$ with positive temperature coefficient
- Fast & soft reverse recovery anti-parallel FWD
- Lead free package

Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply
- Climate compressor

Equivalent Circuit Schematic



Absolute Maximum Ratings T_C=25°C unless otherwise noted

IGBT

Symbol	Description	Values	Unit
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	±20	V
I_C	Collector Current @ T_{vj}=25°C @ T_{vj}=125°C	60 30	A
I_{CM}	Pulsed Collector Current t_p limited by T_{vjmax}	90	A
P_D	Maximum Power Dissipation @ T_{vj}=175°C	208	W

Diode

Symbol	Description	Values	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	650	V
I_F	Diode Continuous Forward Current	30	A
I_{FM}	Diode Maximum Forward Current t_p limited by T_{vjmax}	90	A

Discrete

Symbol	Description	Values	Unit
T_{vjop}	Operating Junction Temperature	-40 to +175	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C
T_S	Soldering Temperature,1.6mm from case for 10s	260	°C
M	Mounting Torque, Screw M3	0.6	N.m

IGBT Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C=30A,V_{GE}=15V, T_{vj}=25°C		1.50	1.95	V
		I_C=30A,V_{GE}=15V, T_{vj}=150°C		1.80		
		I_C=30A,V_{GE}=15V, T_{vj}=175°C		1.80		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	I_C=0.48mA,V_{CE}=V_{GE}, T_{vj}=25°C	5.1	5.8	6.5	V
I_{CES}	Collector Cut-Off Current	V_{CE}=V_{CES},V_{GE}=0V, T_{vj}=25°C			100	uA
I_{GES}	Gate-Emitter Leakage Current	V_{GE}=V_{GES},V_{CE}=0V, T_{vj}=25°C			100	nA
R_{Gint}	Internal Gate Resistance			0		Ω
C_{ies}	Input Capacitance	V_{CE}=25V,f=100kHz, V_{GE}=0V		3.35		nF
C_{res}	Reverse Transfer Capacitance			0.08		nF
Q_G	Gate Charge	V_{GE}=-15…+15V		0.22		uC
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=400V,I_C=30A, R_G=15Ω,L_S=40nH, V_{GE}=±15V,T_{vj}=25°C		20		ns
t_r	Rise Time			36		ns
$t_{d(off)}$	Turn-Off Delay Time			33		ns
t_f	Fall Time			74		ns
E_{on}	Turn-On Switching Loss			0.58		mJ
E_{off}	Turn-Off Switching Loss			0.30		mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=400V,I_C=30A, R_G=15Ω,L_S=40nH, V_{GE}=±15V,T_{vj}=150°C		18		ns
t_r	Rise Time			35		ns
$t_{d(off)}$	Turn-Off Delay Time			35		ns
t_f	Fall Time			95		ns
E_{on}	Turn-On Switching Loss			0.76		mJ
E_{off}	Turn-Off Switching Loss			0.40		mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=400V,I_C=30A, R_G=15Ω,L_S=40nH, V_{GE}=±15V,T_{vj}=175°C		17		ns
t_r	Rise Time			36		ns
$t_{d(off)}$	Turn-Off Delay Time			35		ns
t_f	Fall Time			100		ns
E_{on}	Turn-On Switching Loss			0.84		mJ
E_{off}	Turn-Off Switching Loss			0.43		mJ
I_{SC}	SC Data	t_P≤6μs,V_{GE}=15V, T_{vj}=150 °C,V_{CC}=400V, V_{CEM}≤650V		200		A

Diode Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	I_F=30A,V_{GE}=0V,T_{vj}=25°C		2.25	2.70	V
		I_F=30A,V_{GE}=0V,T_{vj}=150°C		1.65		
		I_F=30A,V_{GE}=0V,T_{vj}=175°C		1.55		
Q_r	Recovered Charge	V_R=400V,I_F=30A, -di/dt=340A/μs,V_{GE}=-15V, L_S=40nH,T_{vj}=25°C		0.13		μC
I_{RM}	Peak Reverse Recovery Current			2.2		A
E_{rec}	Reverse Recovery Energy			0.02		mJ
Q_r	Recovered Charge	V_R=400V,I_F=30A, -di/dt=340A/μs,V_{GE}=-15V, L_S=40nH,T_{vj}=150°C		0.33		μC
I_{RM}	Peak Reverse Recovery Current			5.2		A
E_{rec}	Reverse Recovery Energy			0.03		mJ
Q_r	Recovered Charge	V_R=400V,I_F=30A, -di/dt=350A/μs,V_{GE}=-15V, L_S=40nH,T_{vj}=175°C		0.42		μC
I_{RM}	Peak Reverse Recovery Current			6.1		A
E_{rec}	Reverse Recovery Energy			0.04		mJ

Discrete Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Junction-to-Case (per IGBT) Junction-to-Case (per Diode)			0.720 0.387	K/W
R_{thJA}	Junction-to-Ambient		40		K/W

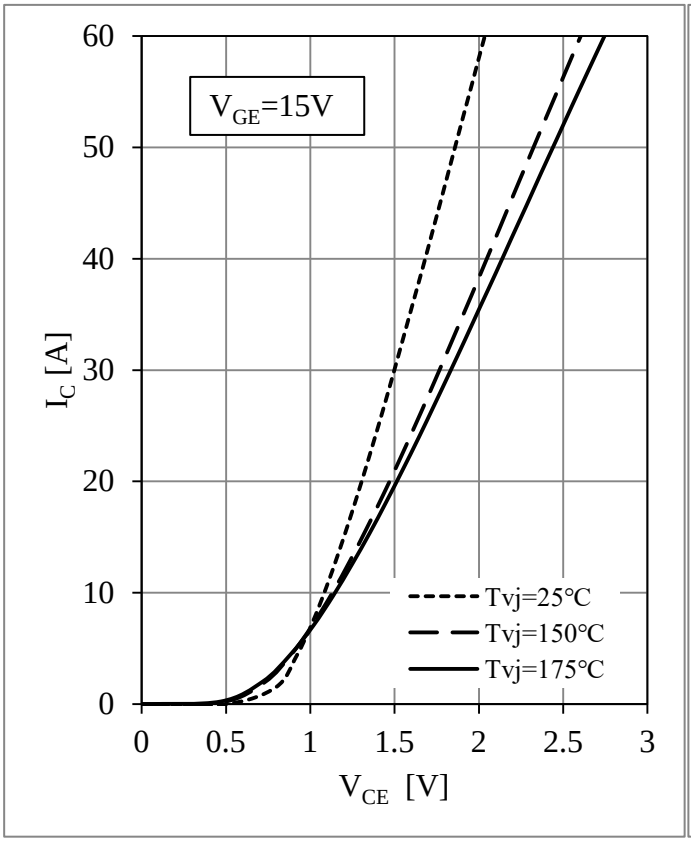


Fig 1. IGBT-inverter Output Characteristics

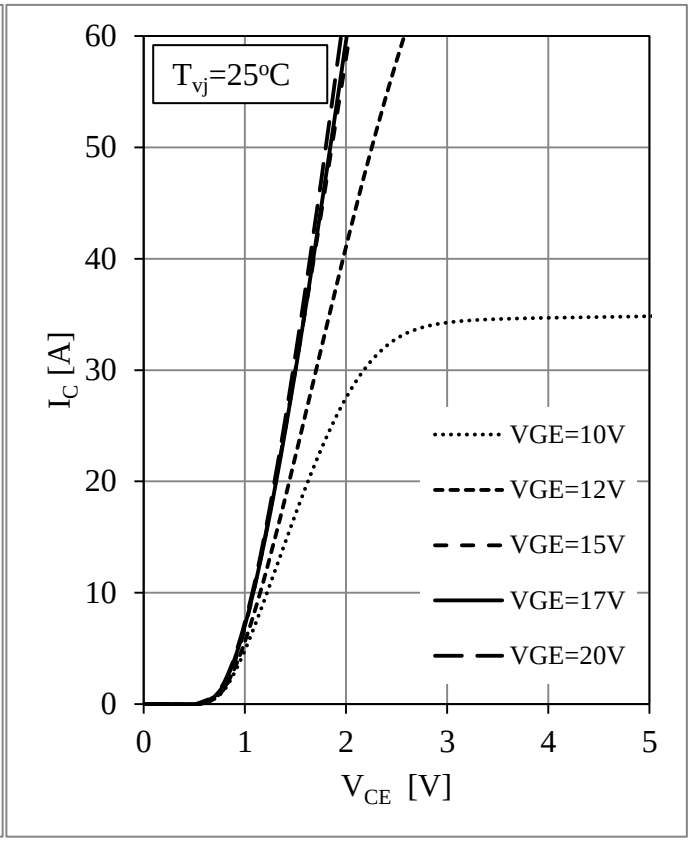


Fig 2. IGBT Output Characteristics

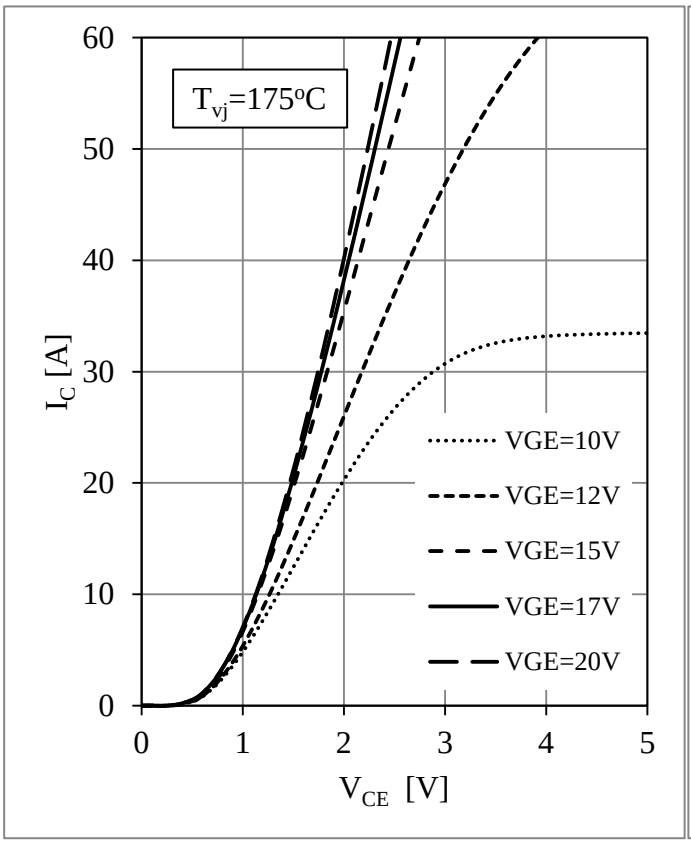


Fig 3. IGBT Output Characteristics

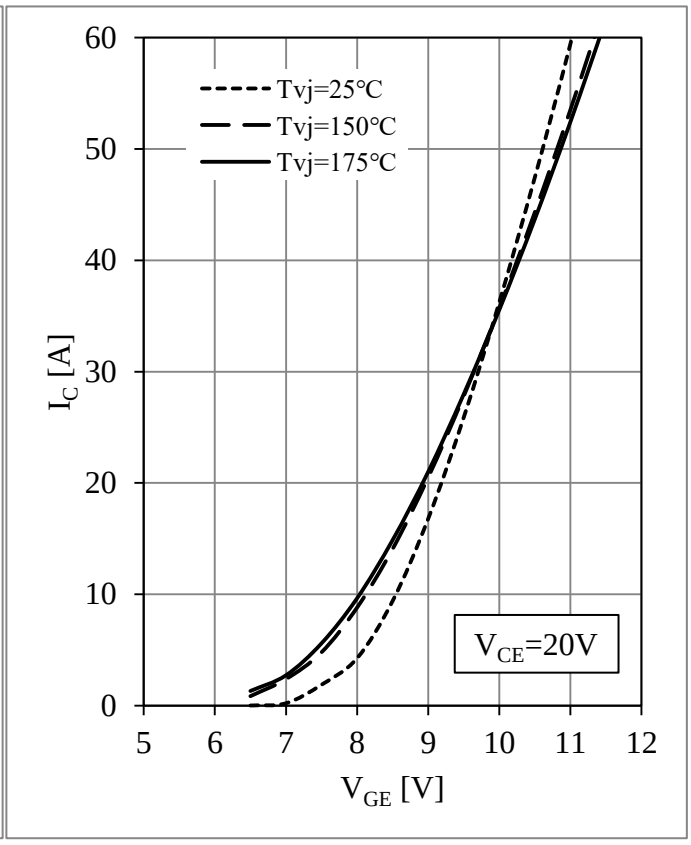


Fig 4. IGBT Transfer Characteristics

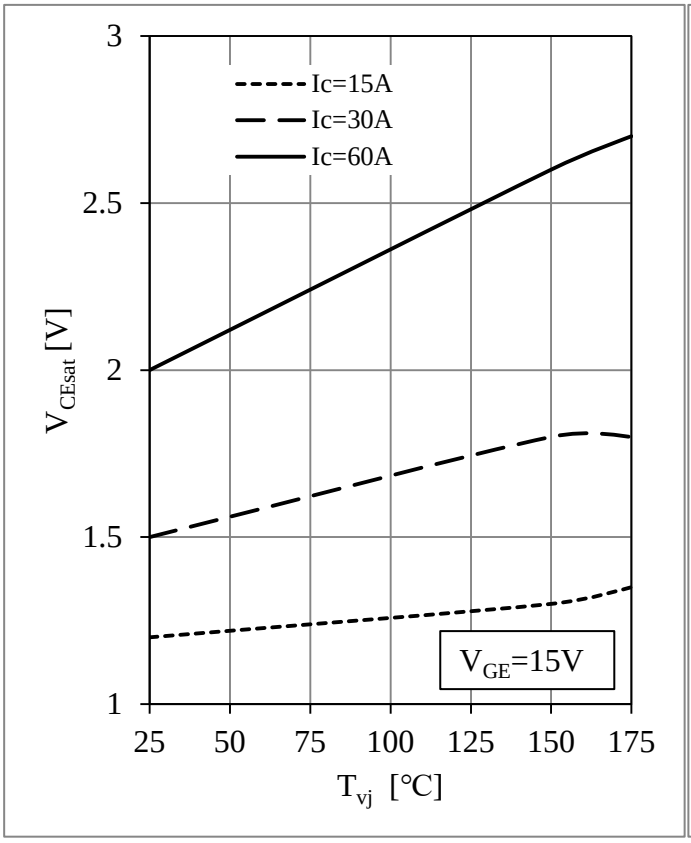


Fig 7. IGBT V_{CEsat} vs. T_{vj}

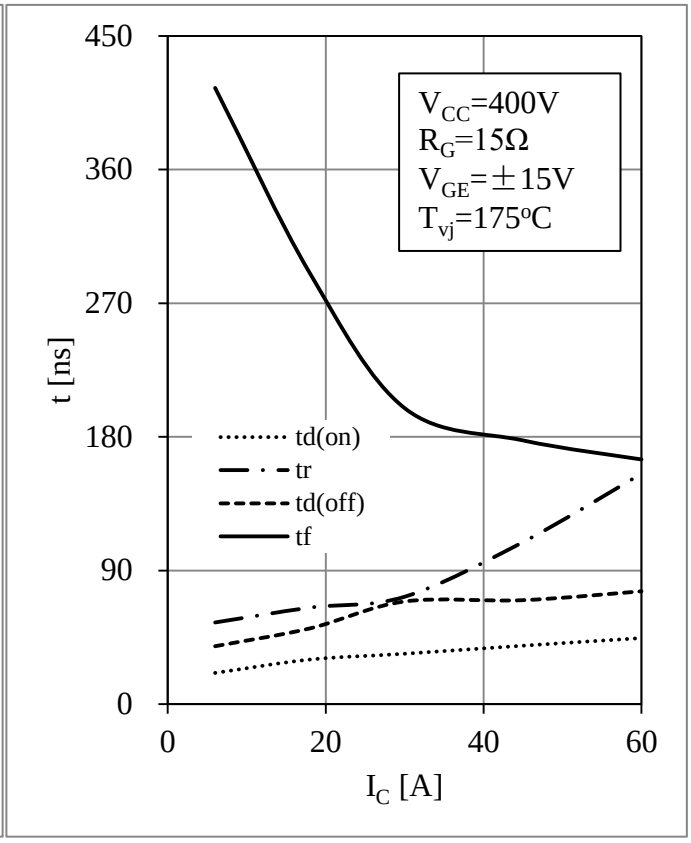


Fig 8. IGBT Switching Times as.I_C

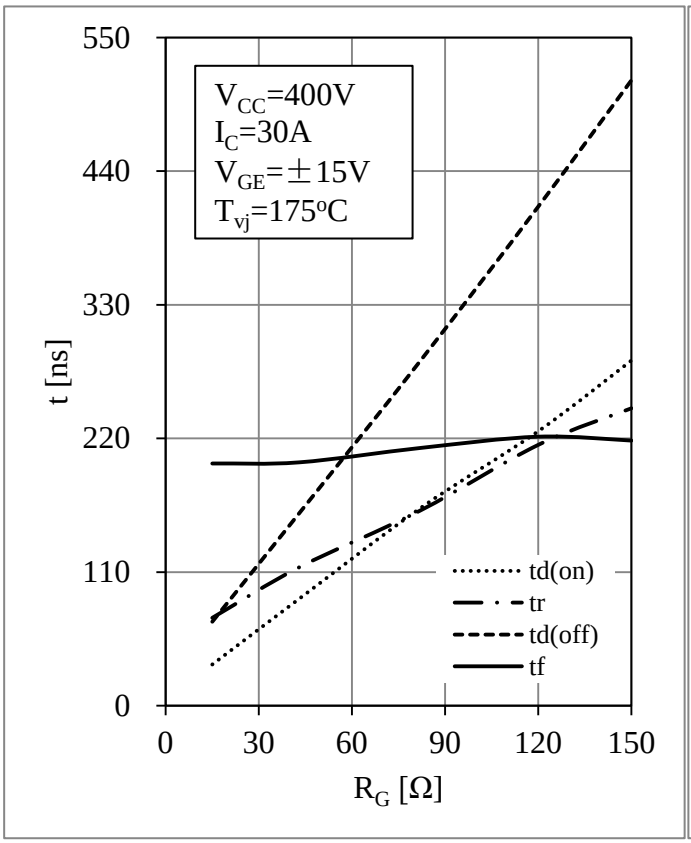


Fig 9. IGBT Switching Times as. R_G

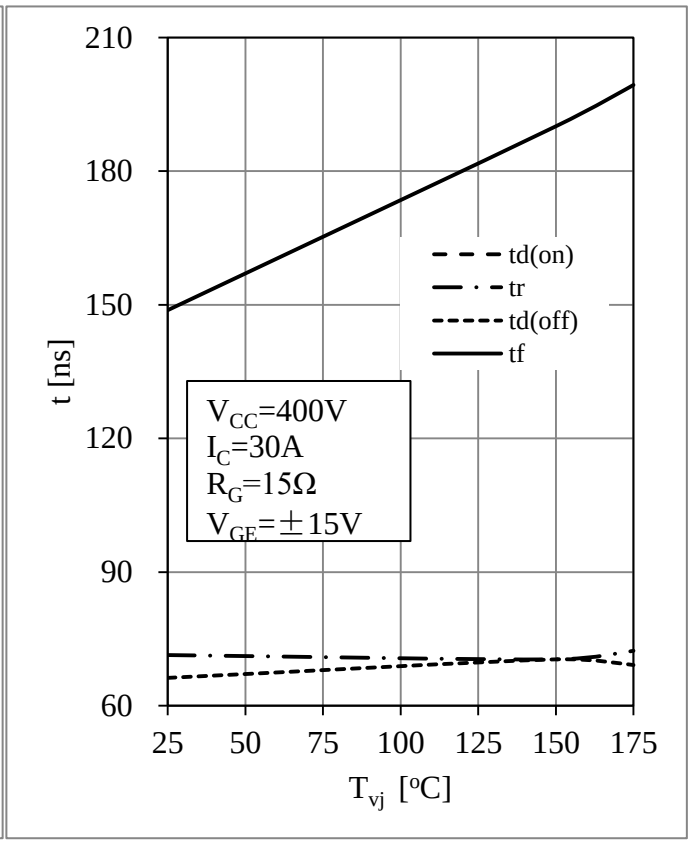


Fig 10. IGBT Switching Times vs. T_{vj}

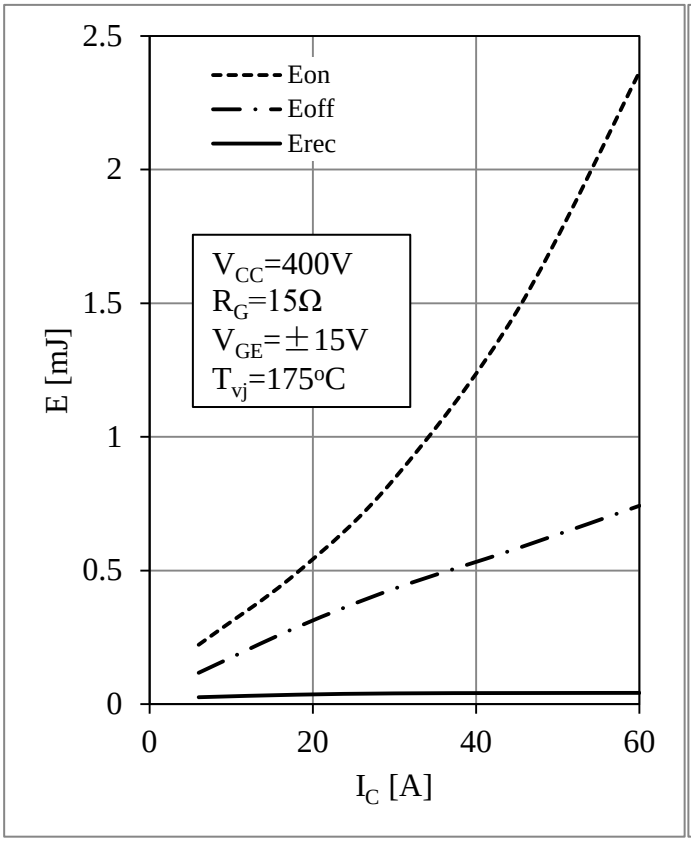


Fig 11. Switching Energy Loss vs. I_C

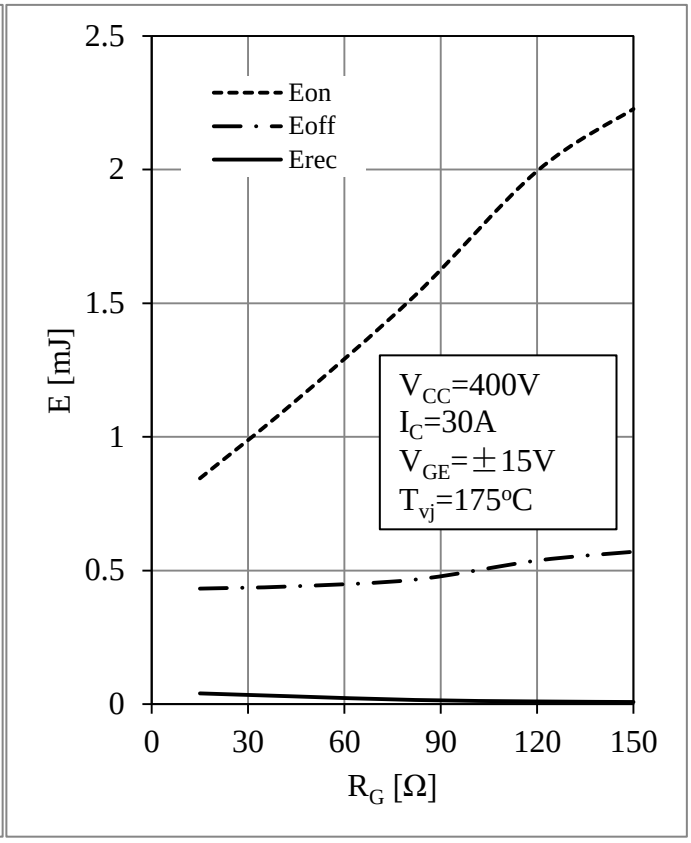


Fig 12 . Switching Energy Loss vs. R_G

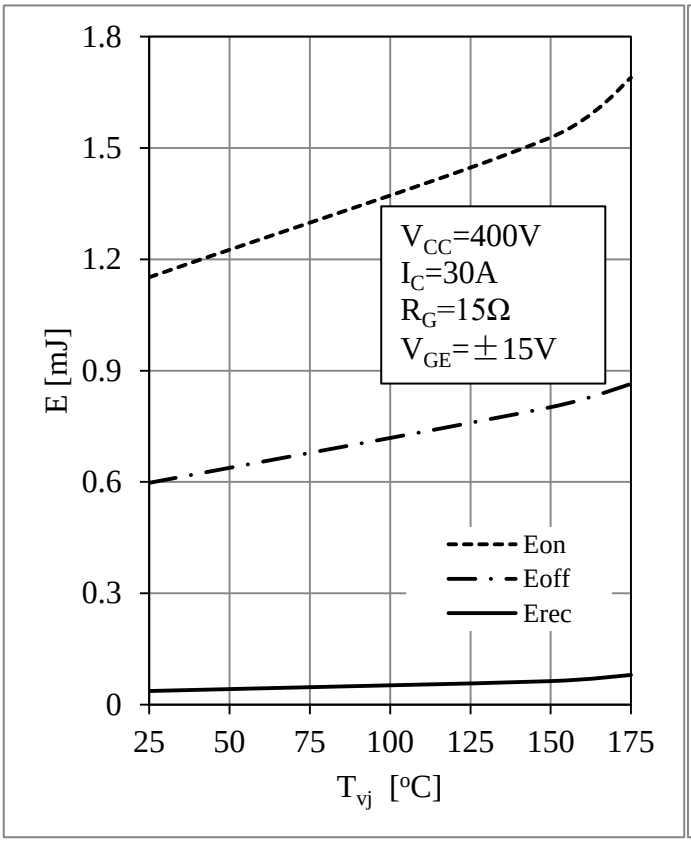


Fig 13. Switching Energy Loss vs. T_{vj}

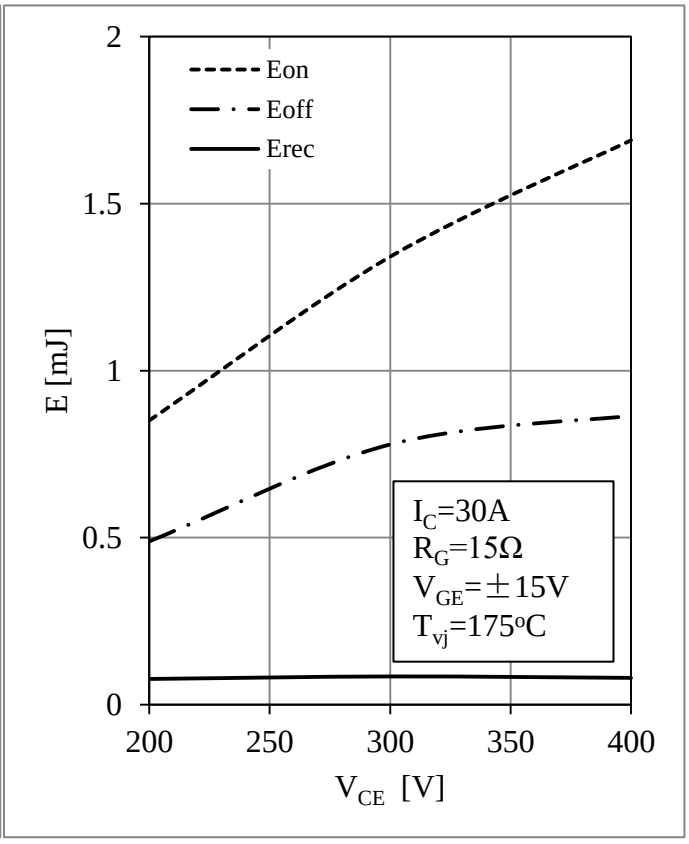


Fig 14 . Switching Energy Loss vs. V_{CE}

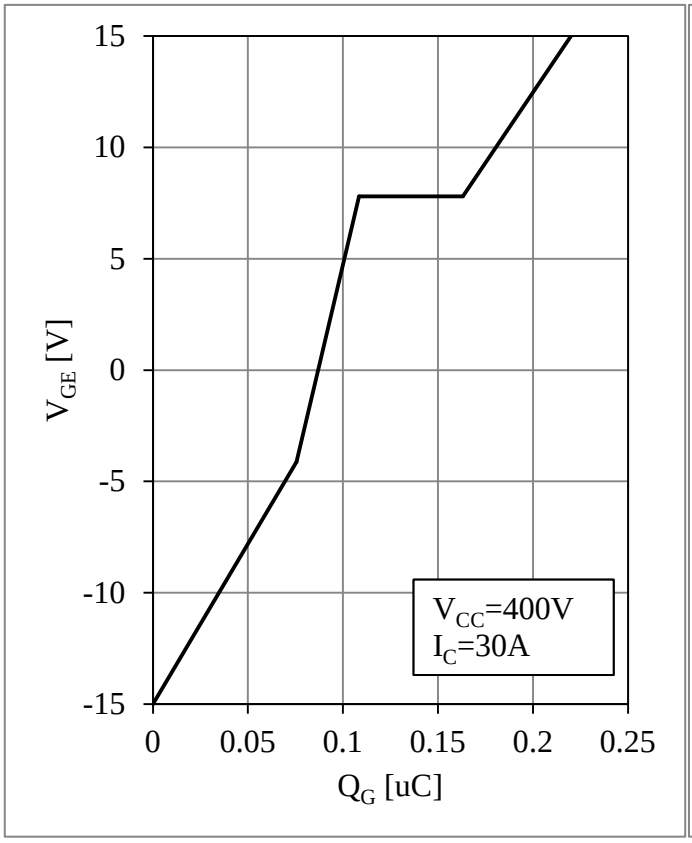


Fig 15. IGBT Gate Charge vs. V_{CE}

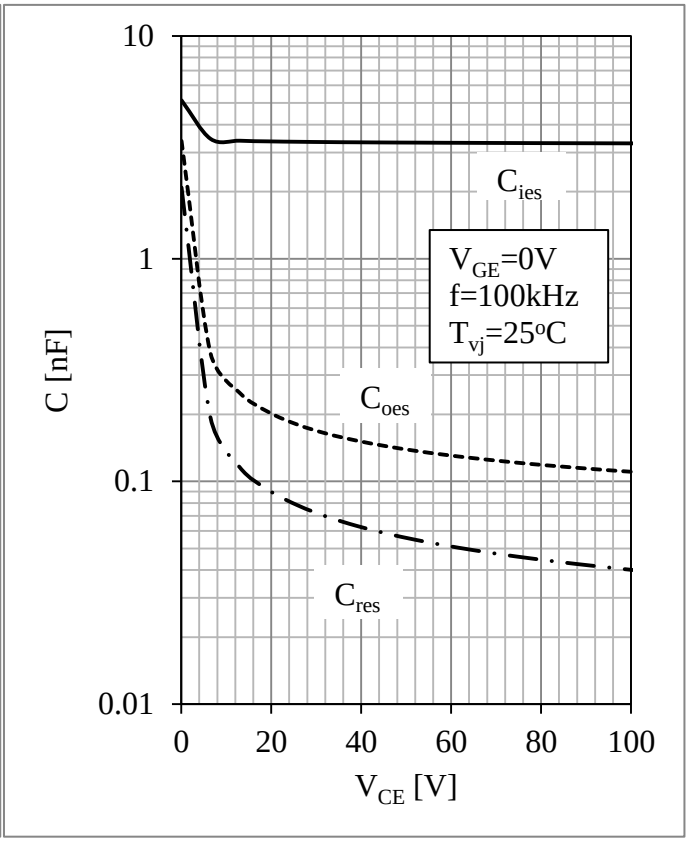


Fig 16. IGBT Capacity Charcteristic

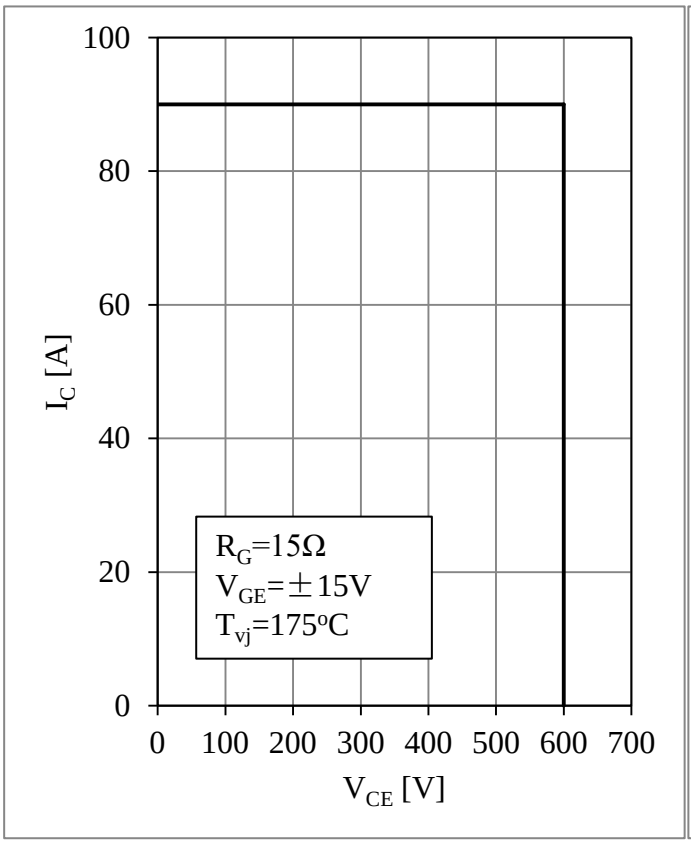


Fig 17. RBSOA

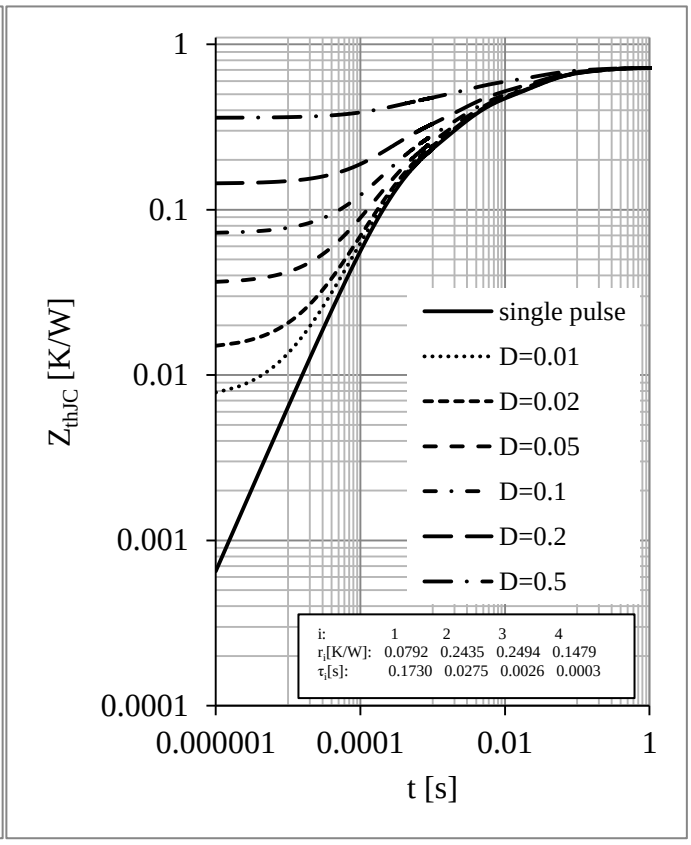


Fig 18. IGBT Transient Thermal Impedance

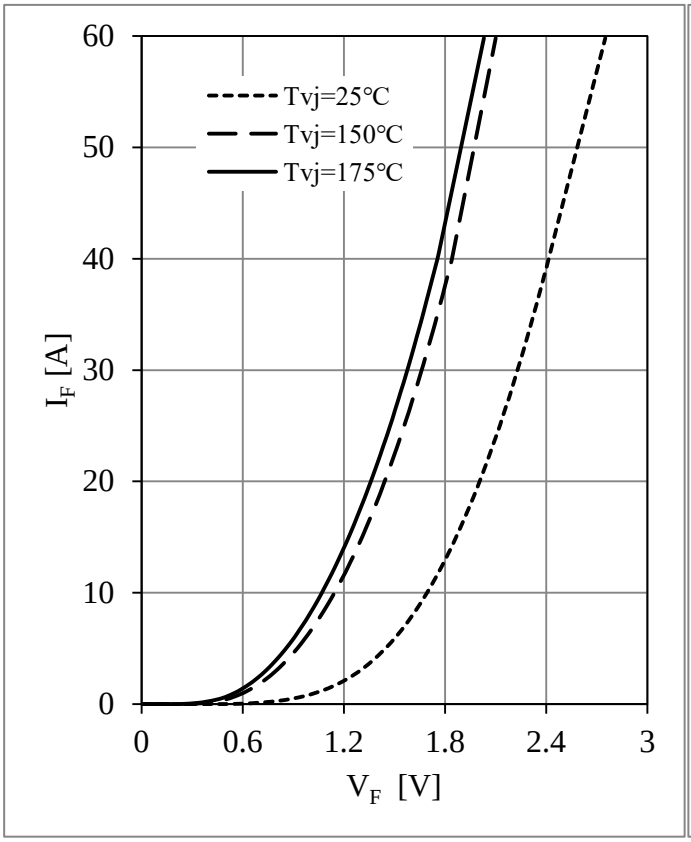


Fig 19. Diode Forward Characteristics

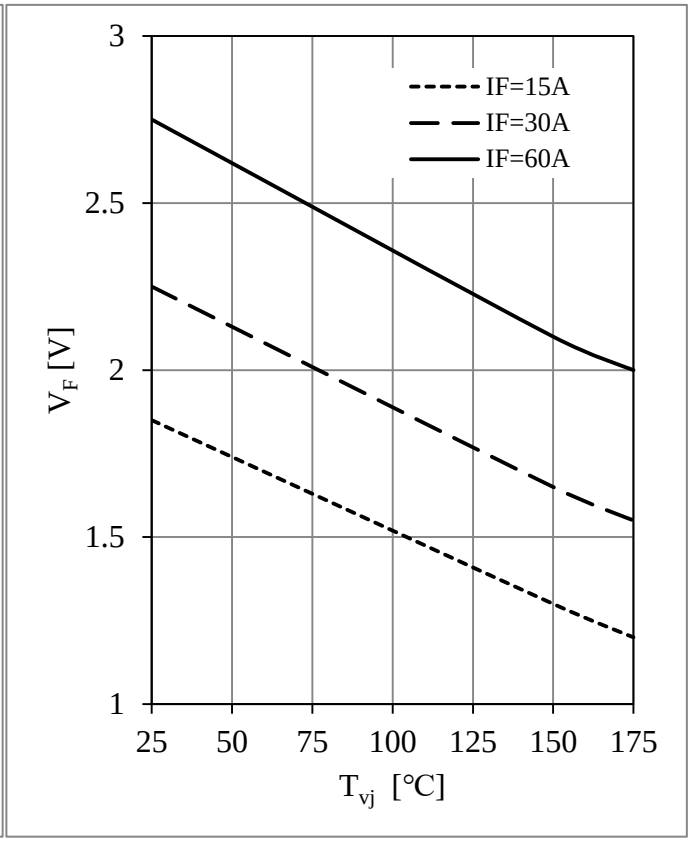


Fig 20. Diode Forward Voltage vs. T_{vj}

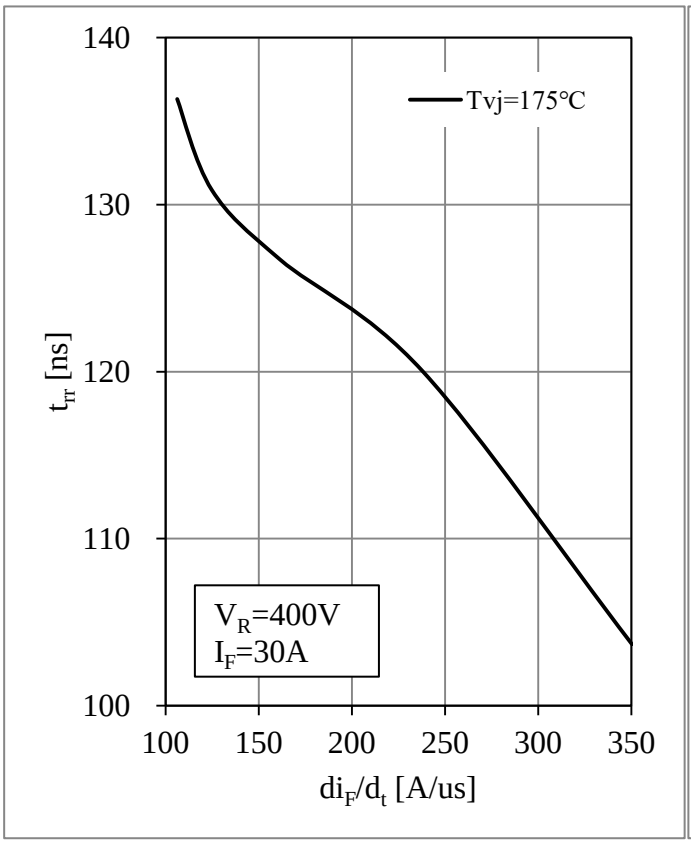


Fig 17. Reverse Recovery Time vs. di_F/d_t

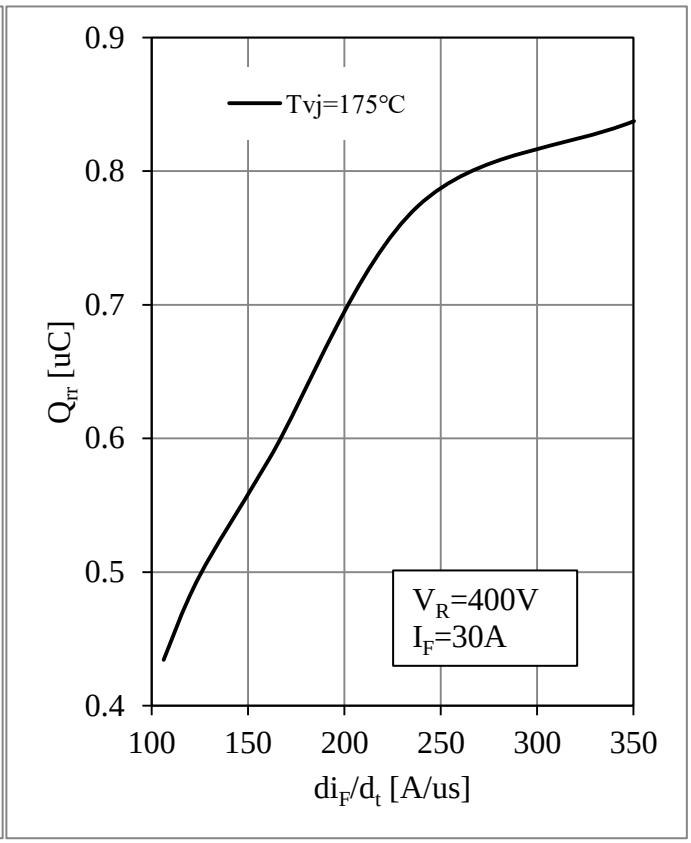


Fig 18. Reverse Recovery Charge vs. di_F/d_t

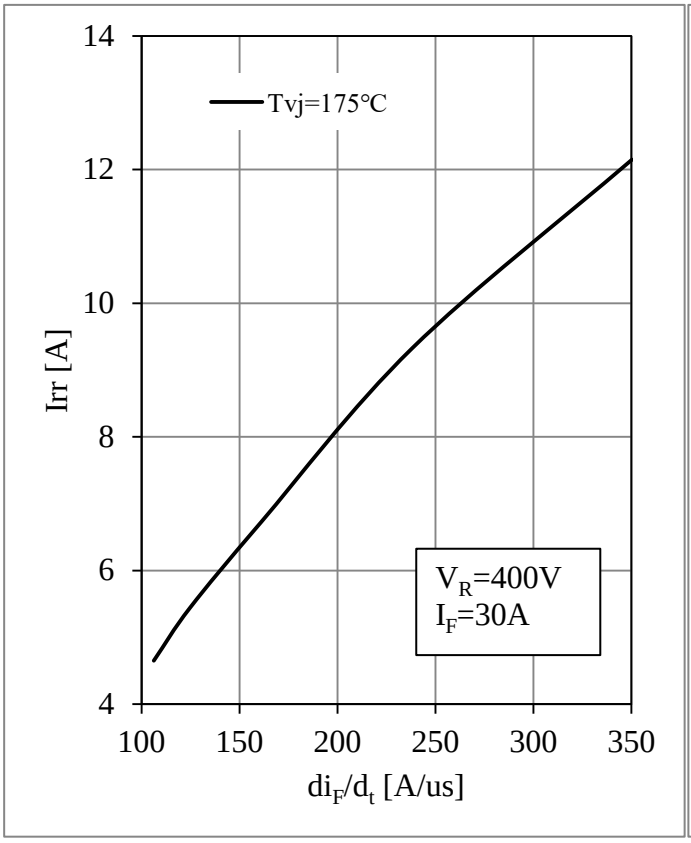


Fig 19. Reverse Recovery Current vs. di_F/d_t

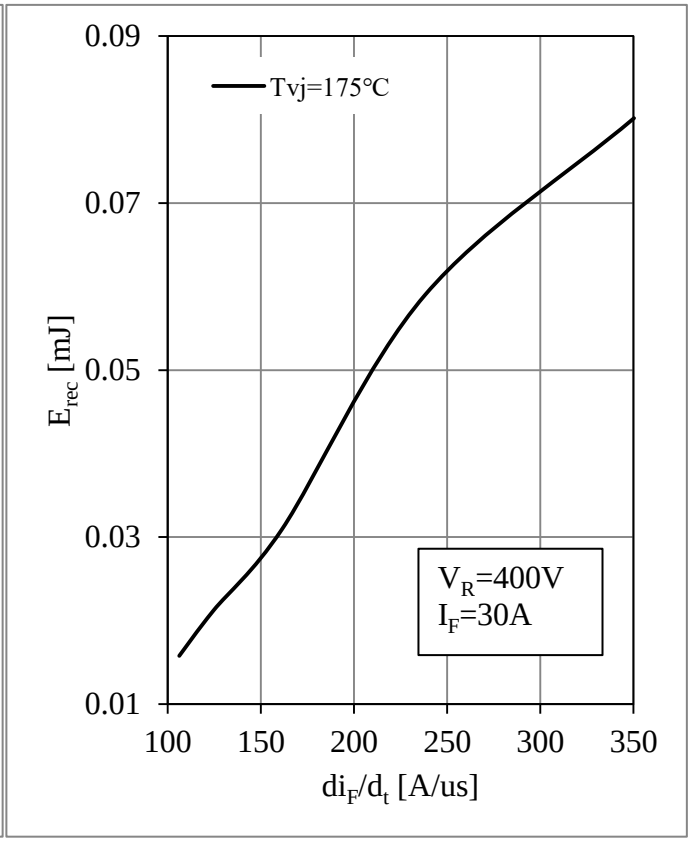


Fig 20. Reverse Energy Losses vs. di_F/d_t

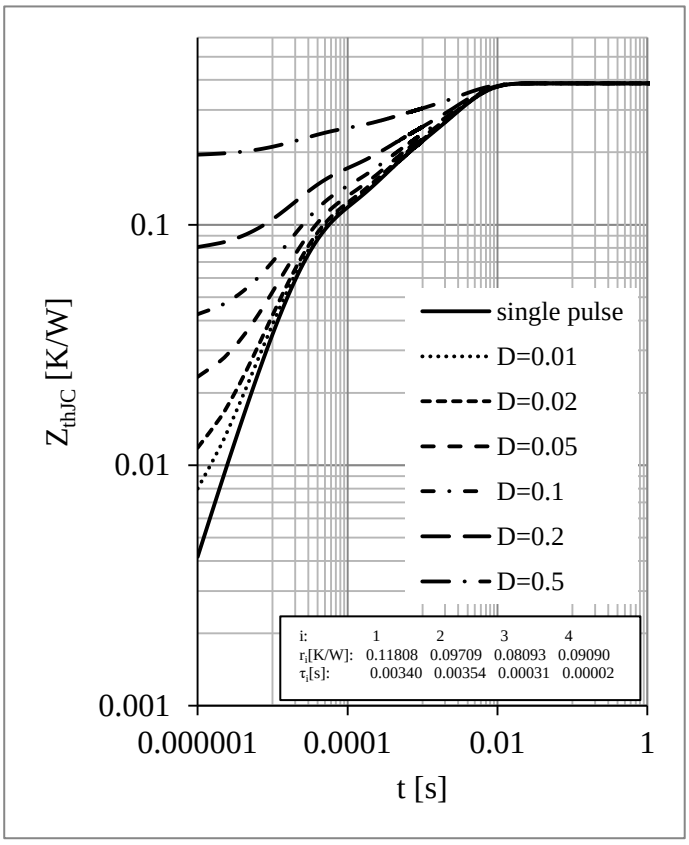
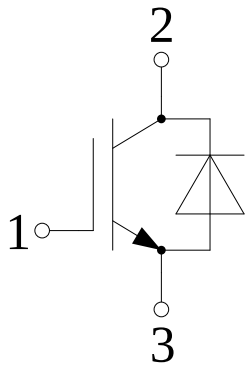


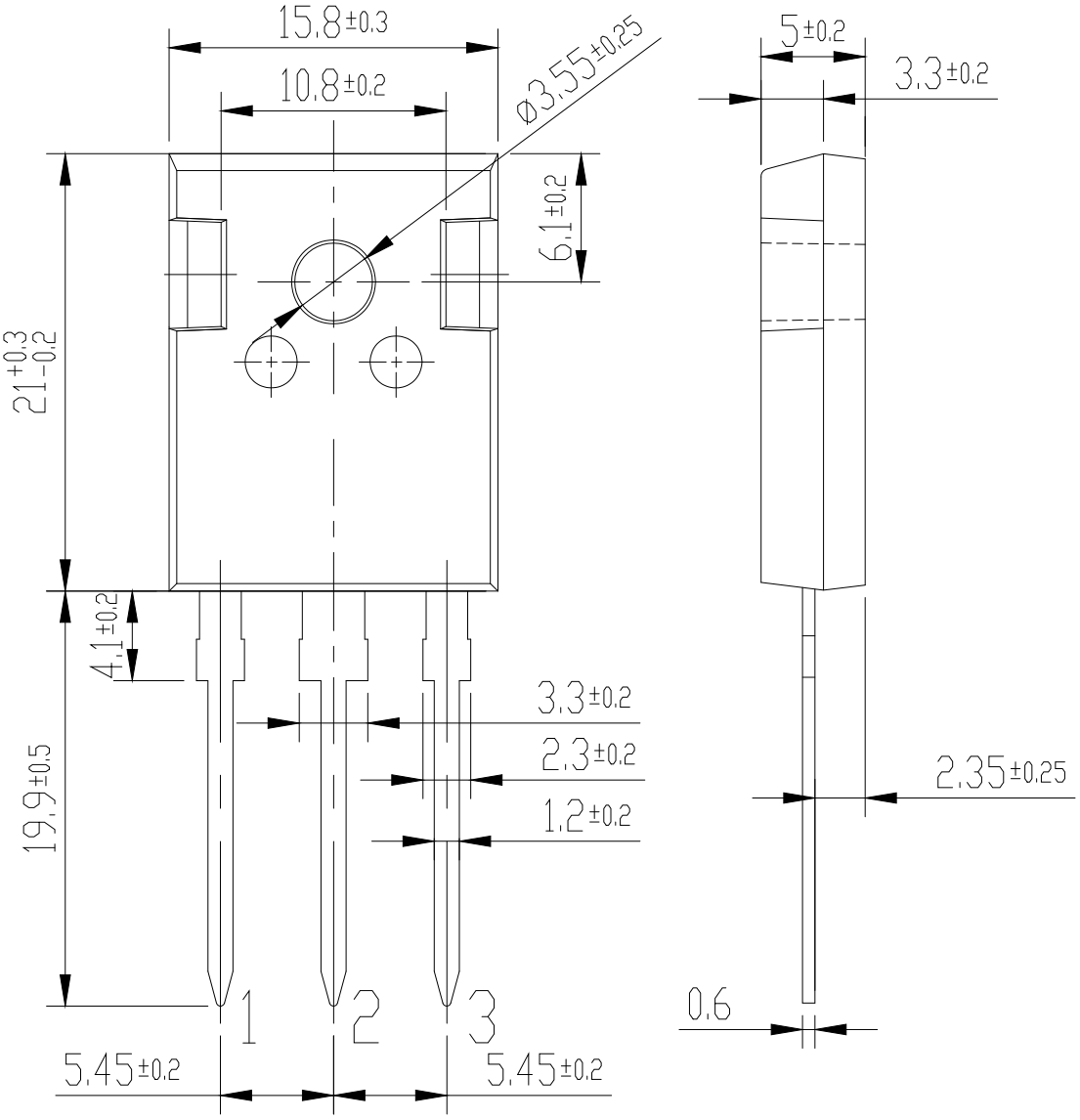
Fig 21. Diode Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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